

6249052

Fig. 1A

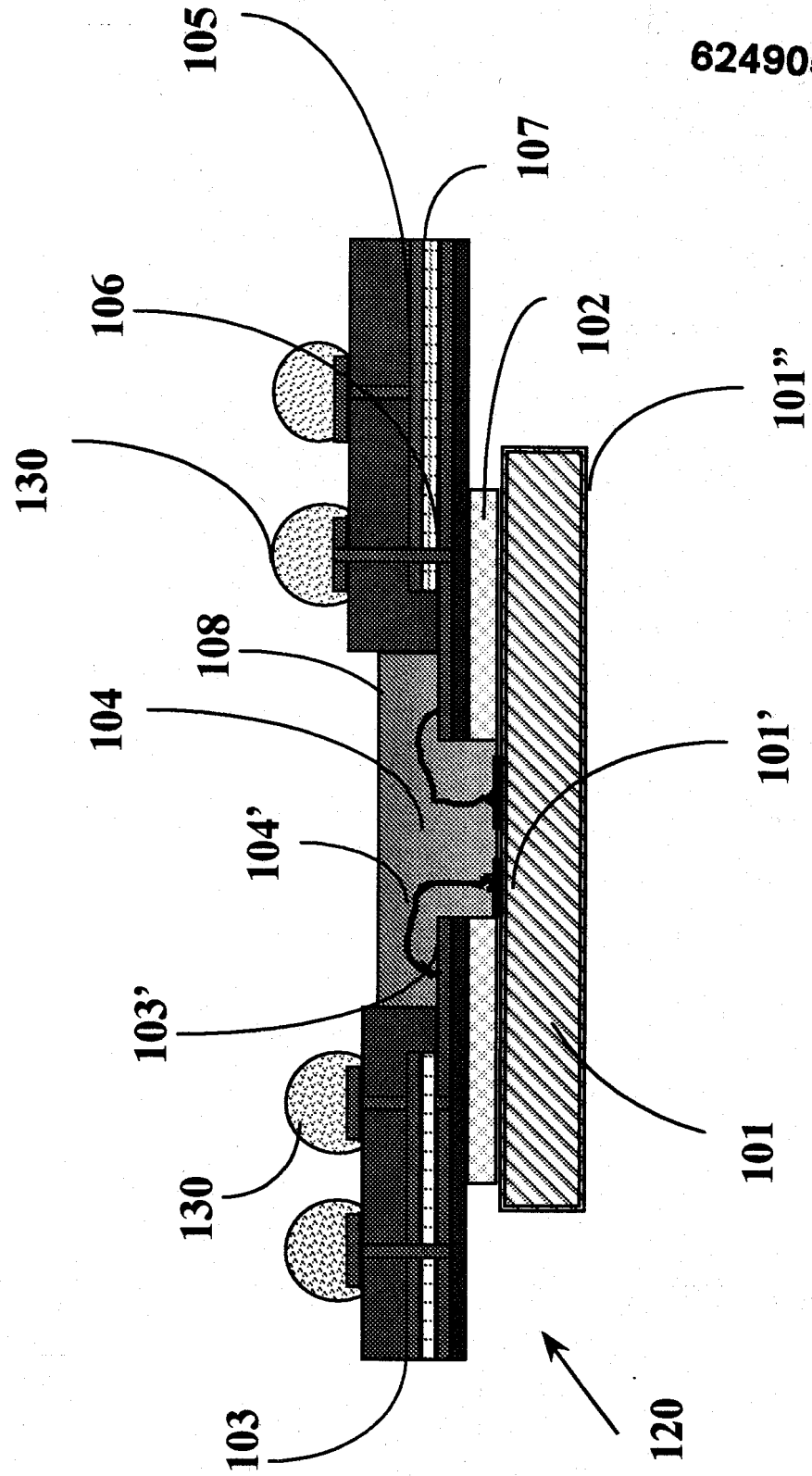


Fig.1B

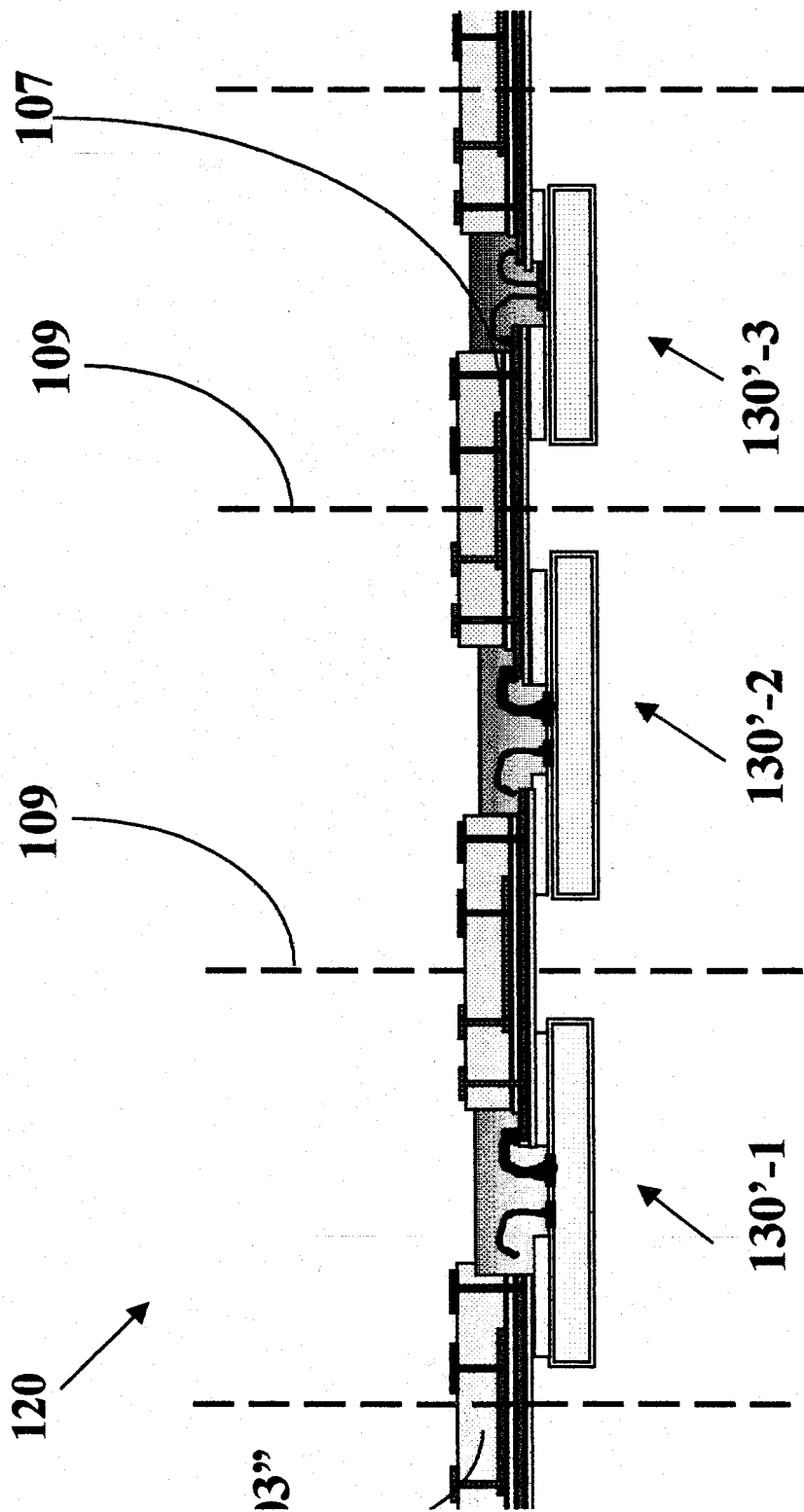




Fig. 1C

Fig. 1D

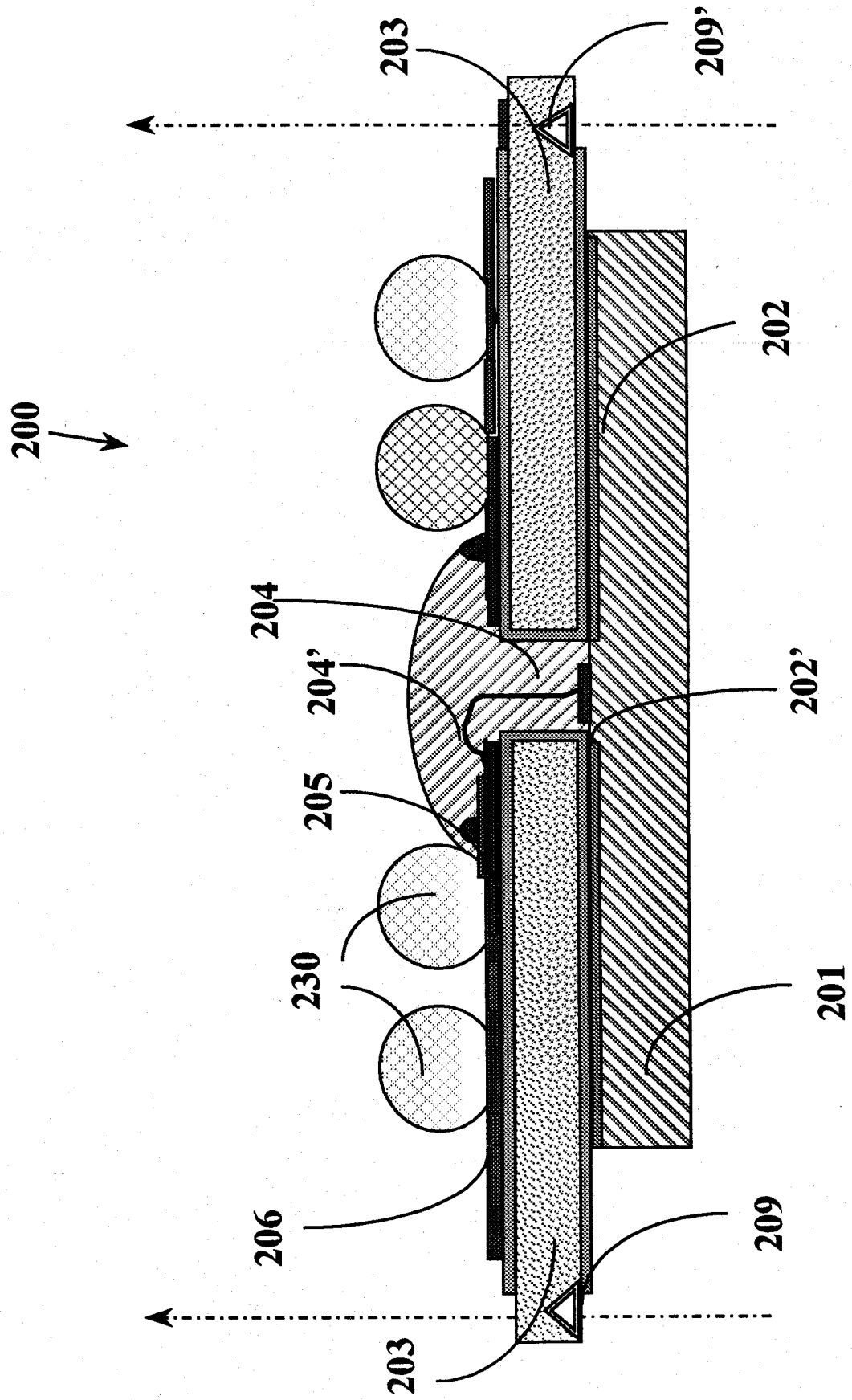


Fig. 2A

300

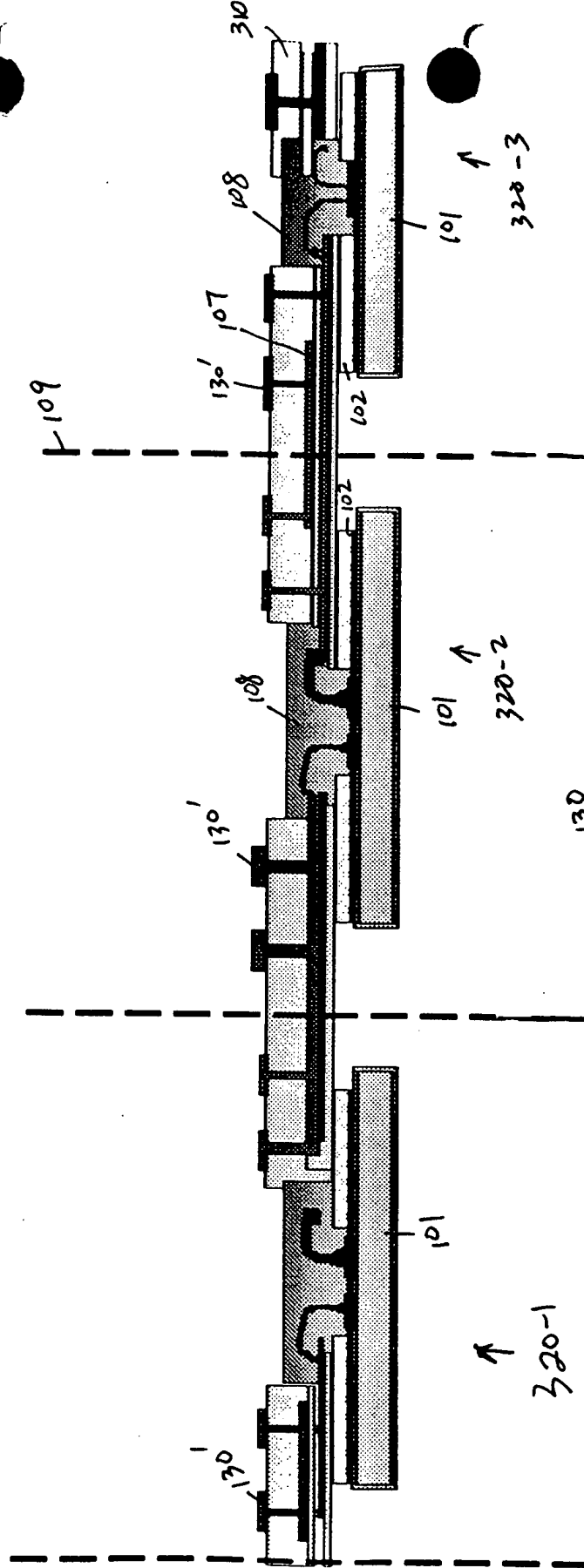


Fig. 2B

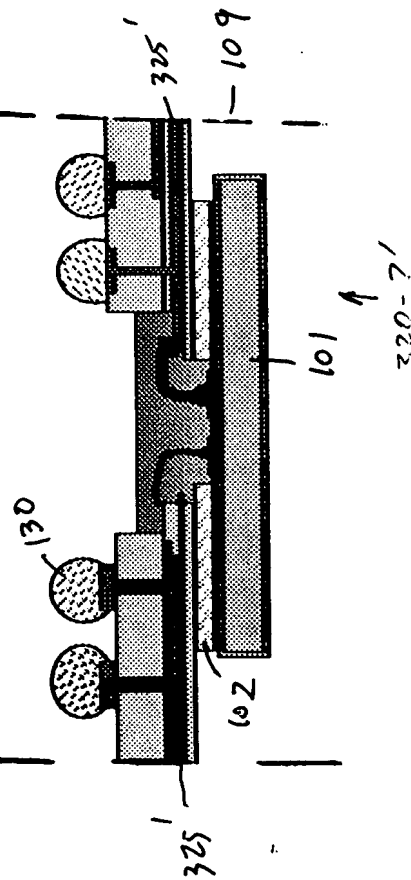


Fig. 2C

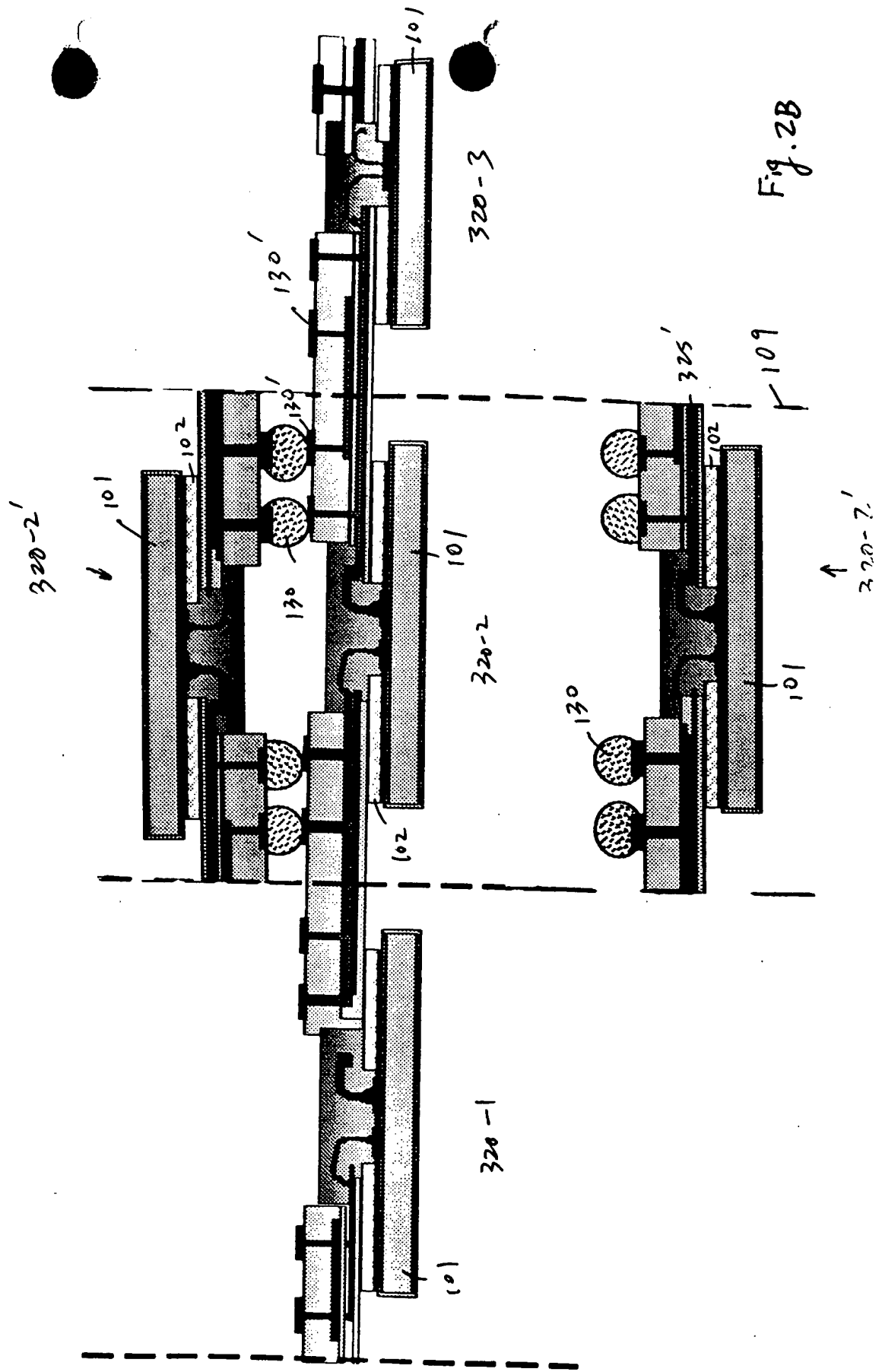


Fig. 2B

300

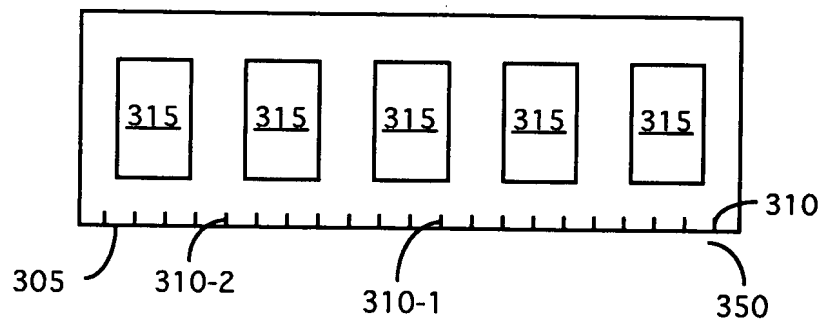


FIG. 3A

300

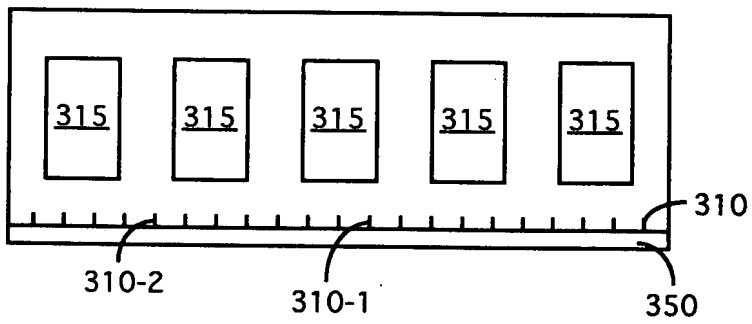


FIG. 3B

CONVENTIONAL MCM FLOW

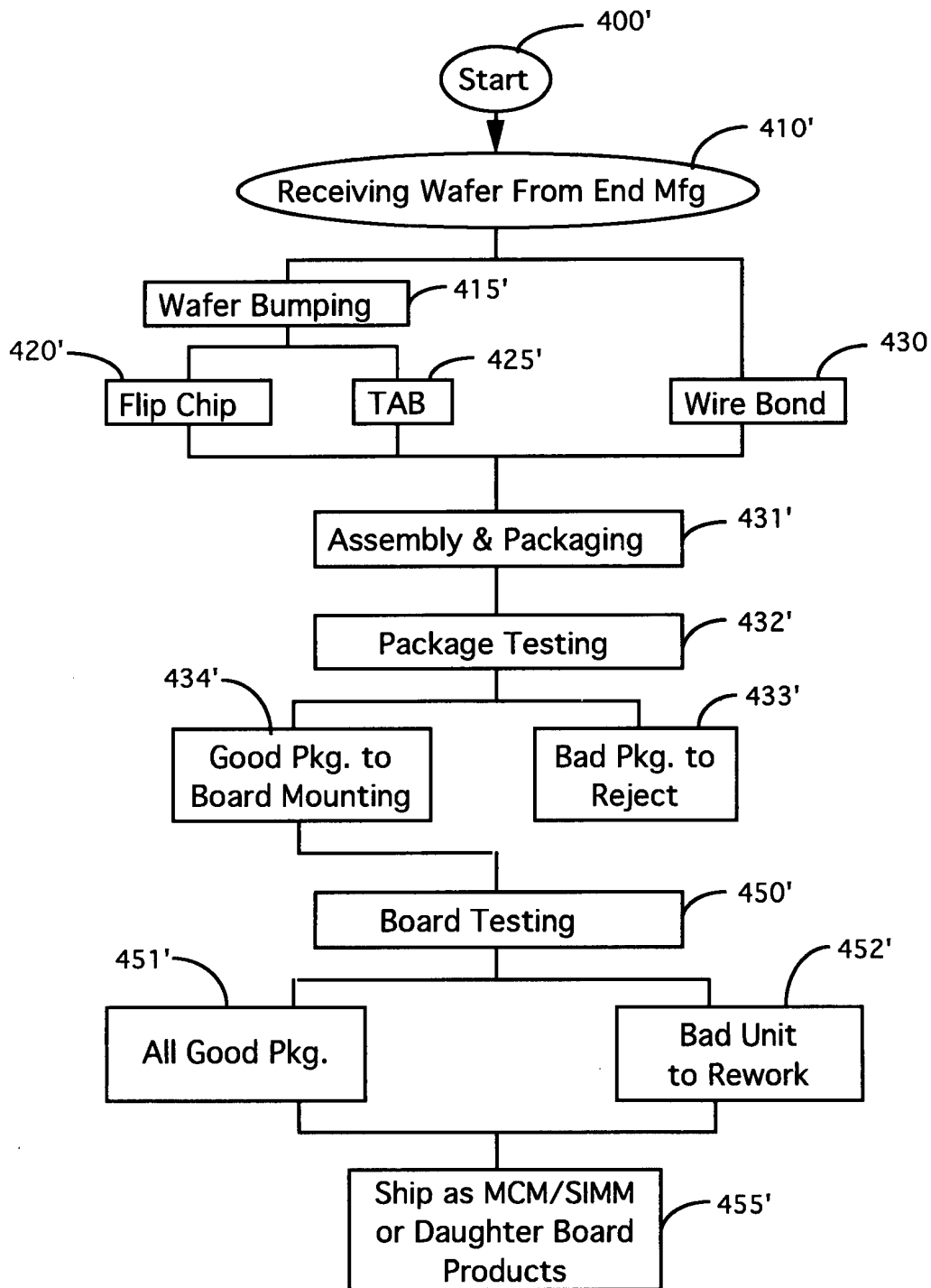


FIG. 4A

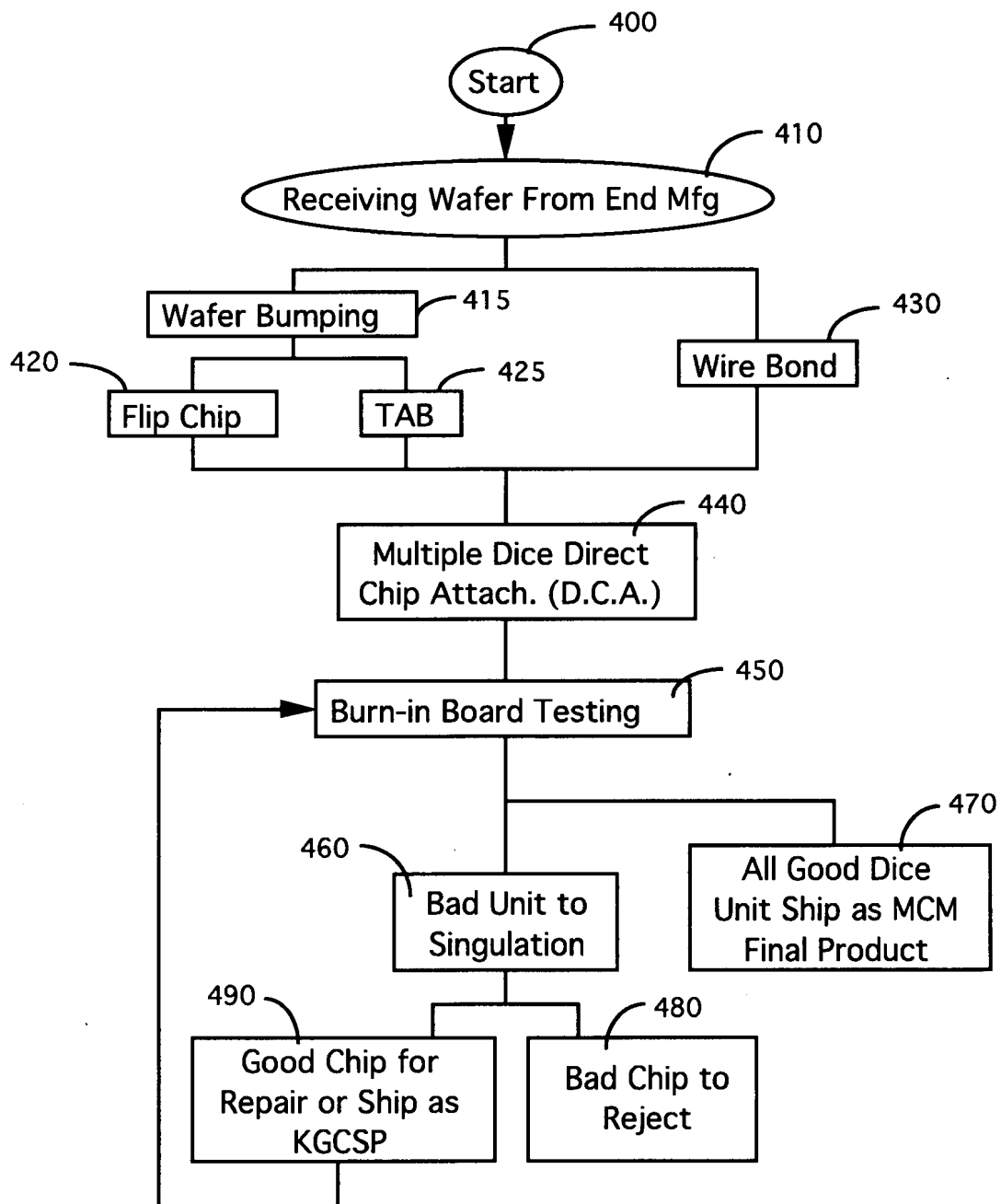


FIG. 4B

Fig. 5

Very Stringent Requirements for SMT Packages

Package Qualification Tests with Level 3 Preconditioning

↓
10 X Temperature Cycle (-65 to +150 deg.C)

↓
Bake of 125 deg.C for 24 Hrs

↓
Temperature Humidity Soak (30 deg.C, 60% RH, 192Hrs)

↓
Vapor Phase (215 deg. C, 60 Sec., 3 Passes)

Thermal Shock Test

Liq. to Liq. -65 to +150 deg.C

1000 Cycles

Temperature Cycle Test

Air to Air, -65 to + 150 deg.C

1,000 Cycles

Autoclave Test

121 deg C,

100% RH

15 PSIG

96 Hrs

Temp.Humidity Bias

85 deg C/85% RH

3.3 Volts

1008 Hrs.

These requirements will not applied on edge connected sub-system such as SIMM/DIMM, PCMCIA or Slot 2 formats.